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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Richard W. Wensel

Serial No.: 10/077,452

Filed: February 14, 2002

For: METHOD AND APPARATUS FOR
TRANSFER MOLDING
ENCAPSULATION OF A
SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK

Confirmation No.: 4093

Examiner: D. Graybill

Group Art Unit: 2827

Attorney Docket No.: 2269-3061.6US
(96-0893.05/US)

Notice of Allowance Mailed:

June 22, 2004

Express Mail Mailing Label No.: EL 994828835 US

Date of Deposit with USPS: September 22, 2004

Person making Deposit: Christopher Haughton

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows: